

# FML12N60ES

**FUJI POWER MOSFET** 

# Super FAP-E<sup>3</sup> series

# **N-CHANNEL SILICON POWER MOSFET**

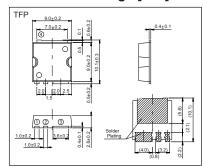
#### ■ Features

Maintains both low power loss and low noise Lower R<sub>DS</sub>(on) characteristic More controllable switching dv/dt by gate resistance Smaller V<sub>GS</sub> ringing waveform during switching Narrow band of the gate threshold voltage (4.2±0.5V) High avalanche durability

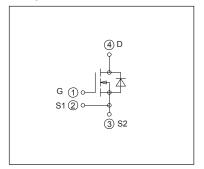
#### Applications

Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

### ■ Outline Drawings [mm]



### ■ Equivalent circuit schematic



## ■ Maximum Ratings and Characteristics

### ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

Description	Symbol	Characteristics	Unit	Remarks
Dunin Course Voltage	V <sub>DS</sub>	600	V	
Drain-Source Voltage	V <sub>DSX</sub>	600	V	V <sub>GS</sub> = -30V
Continuous Drain Current	ID	±12	Α	
Pulsed Drain Current	IDP	±48	Α	
Gate-Source Voltage	V <sub>G</sub> s	±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	Iar	12	Α	Note*1
Non-Repetitive Maximum Avalanche Energy	Eas	384	mJ	Note*2
Repetitive Maximum Avalanche Energy	Ear	18	mJ	Note*3
Peak Diode Recovery dV/dt	dV/dt	4.4	kV/μs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5
Mayimum Dawar Dissination	Ь	1.44	W	Ta=25°C
Maximum Power Dissipation	P□	180	VV	Tc=25°C
O	Tch	150	°C	
Operating and Storage Temperature range	T <sub>stg</sub>	-55 to +150	°C	

#### Electrical Characteristics at Tc=25°C (unless otherwise specified).

Description	Symbol	Conditions		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BVoss	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		600	-	-	V
Gate Threshold Voltage	V <sub>GS</sub> (th)	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		3.7	4.2	4.7	V
Zero Gate Voltage Drain Current		V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	Tch=25°C	-	-	25	μА
	IDSS	V <sub>DS</sub> =480V, V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	-	250	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		10	100	nA
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =6A, V <sub>GS</sub> =10V	I <sub>D</sub> =6A, V <sub>GS</sub> =10V		0.641	0.75	Ω
Forward Transconductance	<b>g</b> fs	I <sub>D</sub> =6A, V <sub>DS</sub> =25V		4	8	-	S
Input Capacitance	Ciss	V <sub>DS</sub> =25V		- 1300 1950			
Output Capacitance	Coss	V <sub>GS</sub> =0V f=1MHz		-	150	225	pF
Reverse Transfer Capacitance	Crss			-	8.5	13	
Turn-On Time	td(on)	V <sub>cc</sub> =300V     -       V <sub>SS</sub> =10V     -       I <sub>D</sub> =6A     -       R <sub>G</sub> =27Ω     -		-	40	60	ns
	tr			-	40	60	
Turn-Off Time	td(off)			74	111	115	
	tf			-	19	29	
Total Gate Charge	Q <sub>G</sub>	Vc=300V In=12A Vcs=10V		-	37	56	nC
Gate-Source Charge	Qss			-	15	23	
Drain-Source Crossover Charge	Qsw			-	6.5	10	
Gate-Drain Charge	Q <sub>GD</sub>			-	12	18	
Avalanche Capability	lav	L=2.64mH, T <sub>ch</sub> =25°C		12	-	-	Α
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =12A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		-	0.86	1.30	V
Reverse Recovery Time	trr	I <sub>F</sub> =12A, V <sub>GS</sub> =0V	I <sub>F</sub> =12A, V <sub>GS</sub> =0V		0.52	-	μS
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25°C		-	5.5	-	μC

#### Thermal Characteristics

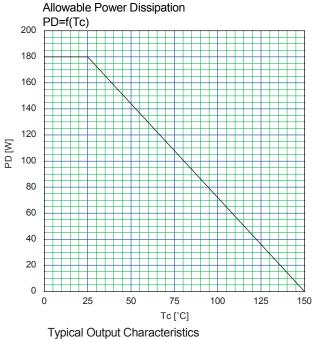
Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to case			0.69	°C/W
	Rth (ch-a)	Channel to Ambient			87	°C/W
	Rth (ch-a)	Channel to Ambient Note*6			52	°C/W

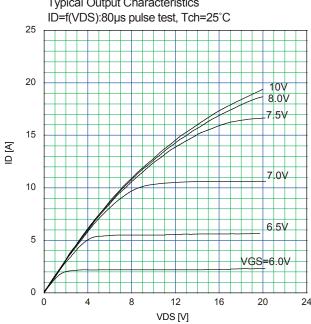
Note \*1 : Tch≤150°C

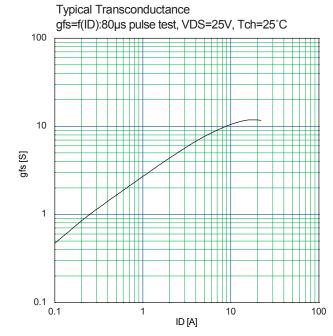
Note \*2 : Stating Tch=25°C, Ias=5A, L=33.8mH, Vcc=50V, R $_{\rm G}$ =10 $\Omega$ , Eas limited by maximum channel temperature and avalanche current. Note \*3 : Repetitive rating : Pulse width limited by maximum channel temperature Note \*4 : IF≤-ID, -di/dt=100A/µs, Vcc≤BVDSS, Tch≤150°C.

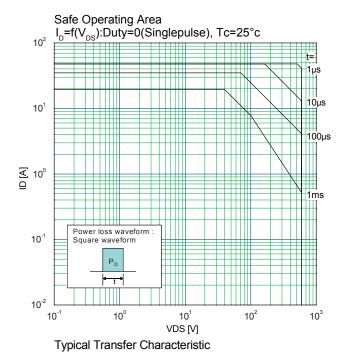
Note \*5 : Ir≤-Ib, dv/dt=6.3kV/Js, Vcc≤BVbss, Tch≤150°C.
Note \*6 : Surface mounted on 1000mm², t=1.6mm FR-4 PCB (Drain pad area : 500mm²)

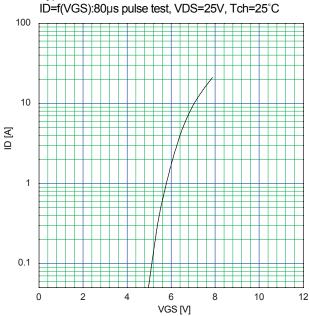
http://www.fujisemi.com

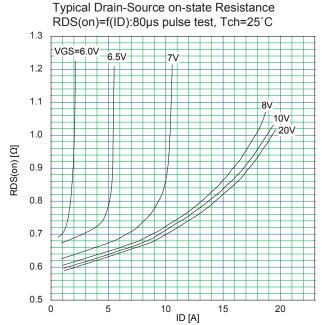


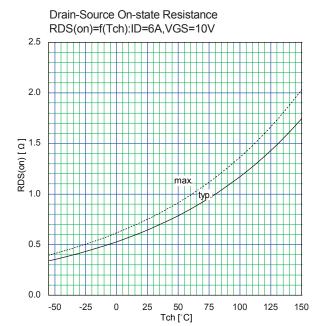




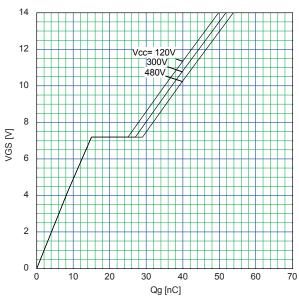




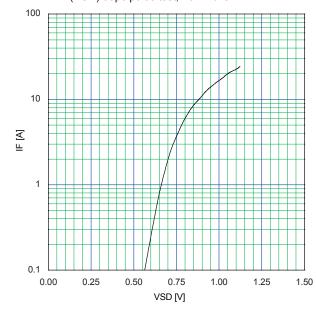




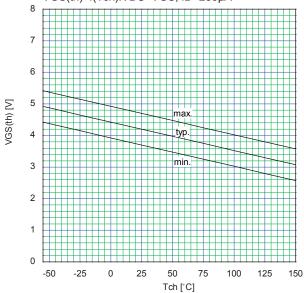
Typical Gate Charge Characteristics VGS=f(Qg):ID=12A, Tch=25°C



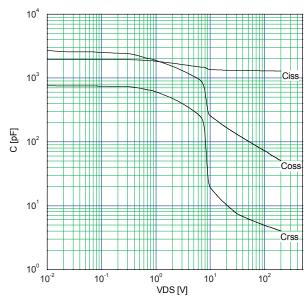
Typical Forward Characteristics of Reverse Diode IF=f(VSD):80µs pulse test, Tch=25°C



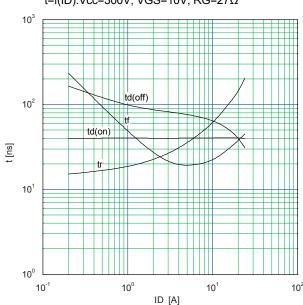
Gate Threshold Voltage vs. Tch VGS(th)=f(Tch):VDS=VGS, ID=250µA



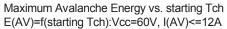
Typical Capacitance C=f(VDS):VGS=0V, f=1MHz

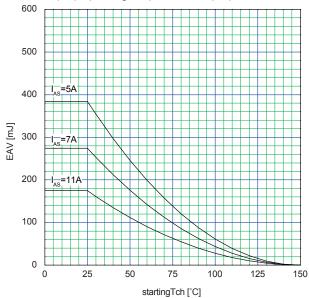


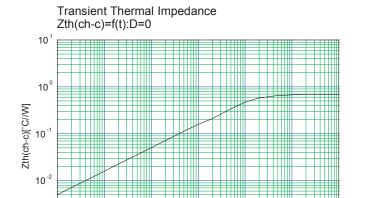
Typical Switching Characteristics vs. ID t=f(ID):Vcc=300V, VGS=10V, RG=27 $\Omega$ 



http://www.fujisemi.com







10<sup>-3</sup>

t [sec]

10<sup>-2</sup>

10

10°

10-4

10<sup>-5</sup>

10<sup>-3</sup>

10

http://www.fujisemi.com

#### WARNING

- 1. This Catalog contains the product specifications, characteristics, data, materials, and structures as of March 2010.

  The contents are subject to change without notice for specification changes or other reasons. When using a product listed in this Catalog, be sure to obtain the latest specifications.
- 2. All applications described in this Catalog exemplify the use of Fuji's products for your reference only. No right or license, either express or implied, under any patent, copyright, trade secret or other intellectual property right owned by Fuji Electric Systems Co., Ltd. is (or shall be deemed) granted. Fuji Electric Systems Co., Ltd. makes no representation or warranty, whether express or implied, relating to the infringement or alleged infringement of other's intellectual property rights which may arise from the use of the applications described herein.
- 3. Although Fuji Electric Systems Co., Ltd. is enhancing product quality and reliability, a small percentage of semiconductor products may become faulty. When using Fuji Electric semiconductor products in your equipment, you are requested to take adequate safety measures to prevent the equipment from causing a physical injury, fire, or other problem if any of the products become faulty. It is recommended to make your design fail-safe, flame retardant, and free of malfunction.
- 4. The products introduced in this Catalog are intended for use in the following electronic and electrical equipment which has normal reliability requirements.
  - Computers
     OA equipment
- Communications equipment (terminal devices)
- Measurement equipment

- Machine tools
- Audiovisual equipment
- Electrical home appliances Per
- Personal equipment Industrial robots etc.
- 5. If you need to use a product in this Catalog for equipment requiring higher reliability than normal, such as for the equipment listed below, it is imperative to contact Fuji Electric Systems Co., Ltd. to obtain prior approval. When using these products for such equipment, take adequate measures such as a backup system to prevent the equipment from malfunctioning even if a Fuji's product incorporated in the equipment becomes faulty.
  - Transportation equipment (mounted on cars and ships)
- Trunk communications equipment

• Traffic-signal control equipment

- Gas leakage detectors with an auto-shut-off feature
- $\bullet$  Emergency equipment for responding to disasters and anti-burglary devices
- Safety devices

- Medical equipment
- 6. Do not use products in this Catalog for the equipment requiring strict reliability such as the following and equivalents to strategic equipment (without limitation).
  - Space equipment Aeronautic equipment
- Nuclear control equipment
- Submarine repeater equipment
- 7. Copyright @1996-2008 by Fuji Electric Systems Co., Ltd. All rights reserved.

  No part of this Catalog may be reproduced in any form or by any means without the express permission of Fuji Electric Systems Co., Ltd.
- 8. If you have any question about any portion in this Catalog, ask Fuji Electric Systems Co., Ltd. or its sales agents before using the product.
  - Neither Fuji Electric Systems Co., Ltd. nor its agents shall be liable for any injury caused by any use of the products not in accordance with instructions set forth herein.